



Material Content Data Sheet



Sales Product Name		BSC0993ND		Issued		23. January 2018		
MA#		MA001587144						
Package		PG-TISON-8-2		Weight*		96.01 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.210	0.22	0.22	2192	2192
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		107	
	non noble metal	zinc	7440-66-6	0.041	0.04		428	
	non noble metal	iron	7439-89-6	0.822	0.86		8557	
wire	non noble metal	copper	7440-50-8	33.360	34.75	35.66	347457	356549
	noble metal	gold	7440-57-5	0.063	0.07	0.07	651	651
encapsulation	organic material	carbon black	1333-86-4	0.096	0.10		1004	
	plastics	epoxy resin	-	4.967	5.17		51729	
leadfinish	inorganic material	silicondioxide	60676-86-0	43.157	44.95	50.22	449491	502224
	non noble metal	tin	7440-31-5	1.122	1.17	1.17	11684	11684
	noble metal	silver	7440-22-4	0.186	0.19	0.19	1935	1935
solder	noble metal	silver	7440-22-4	0.009	0.01		97	
	non noble metal	tin	7440-31-5	0.007	0.01		77	
heat sink CLIP	non noble metal	lead	7439-92-1	0.355	0.37	0.39	3694	3868
	inorganic material	phosphorus	7723-14-0	0.003	0.00		36	
	non noble metal	zinc	7440-66-6	0.014	0.01		145	
	non noble metal	iron	7439-89-6	0.279	0.29		2902	
*deviation	non noble metal	copper	7440-50-8	11.312	11.78	12.08	117814	120897
	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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